



Supporting Information

for

Controllable physicochemical properties of WO_x thin films grown under glancing angle

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Supplementary data

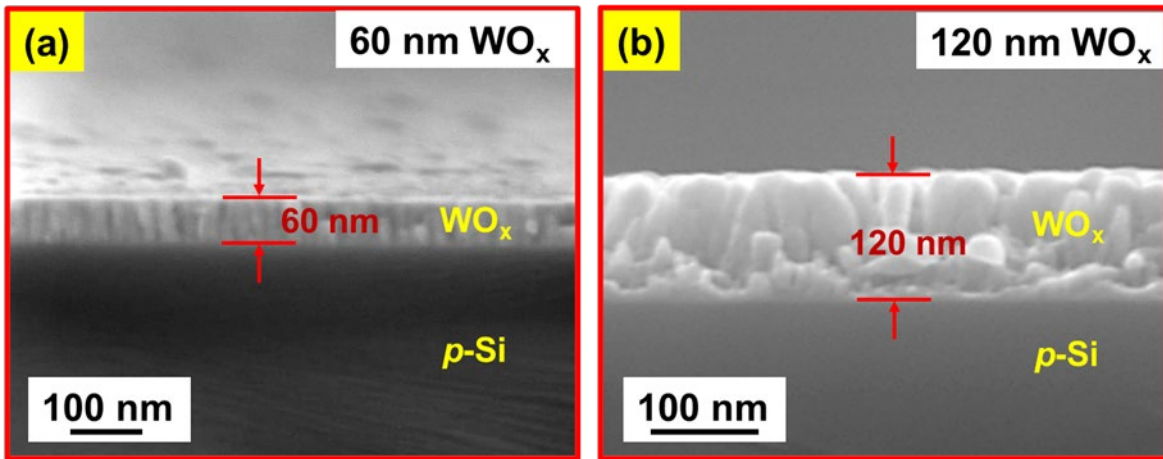


Figure S1: (a, b) XSEM images of 60 and 120 nm thick WO_x thin films deposited on p-Si substrates.

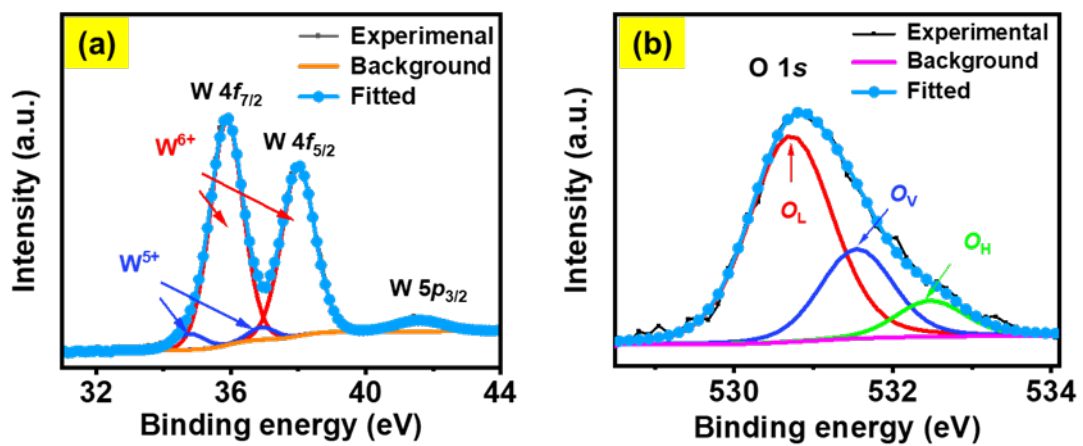


Figure S2: (a, b) XPS W 4f and O 1s core level spectra of as-deposited WO_x films having a thickness of 30 nm.

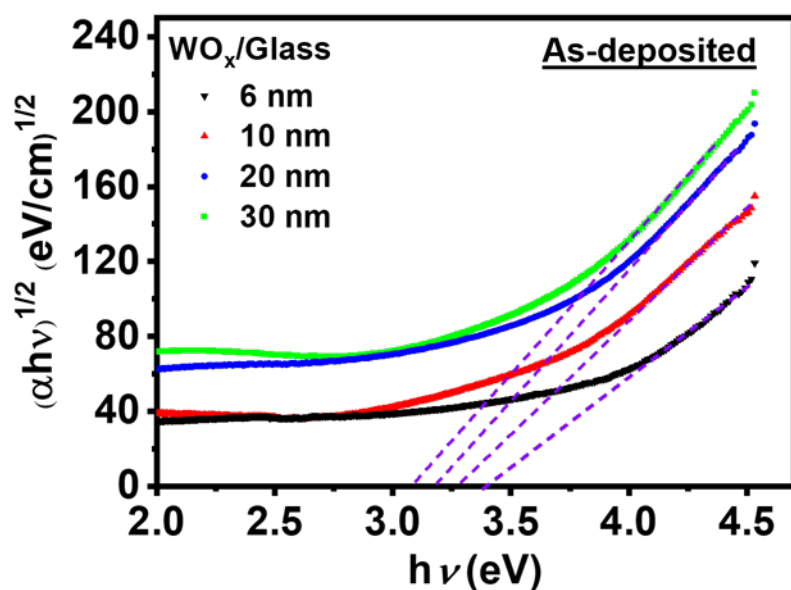


Figure S3: Tauc plots of the as-deposited nanostructured WO_x for different film thicknesses. The dashed lines indicate the intercept of the extrapolates on the x axis, providing the corresponding bandgap energies.

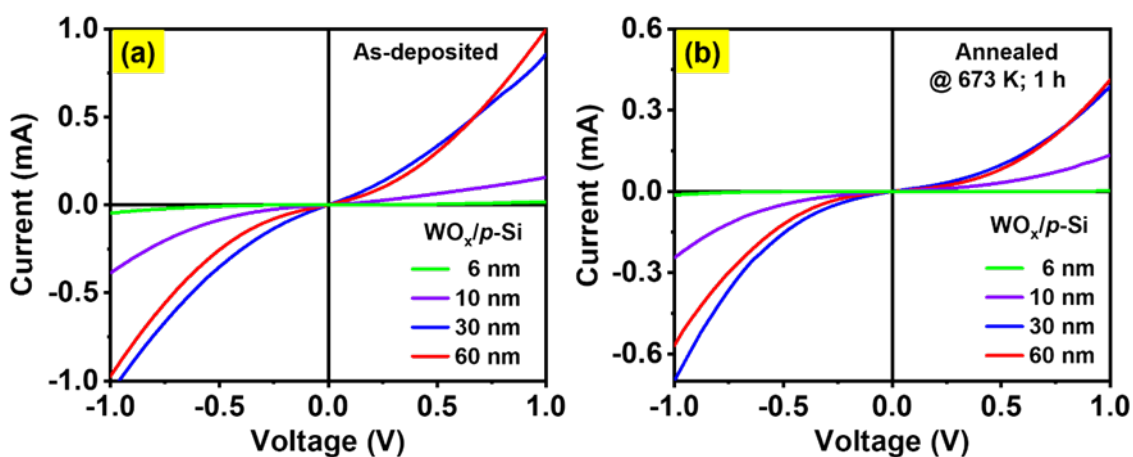


Figure S4: Linear I - V curves of (a) as-deposited and (b) annealed $\text{WO}_x/p\text{-Si}$ heterostructures for different WO_x film thicknesses.

Table S1: Comparison between the present work and previously reported works on nanostructured WO₃ films.

Film thickness (nm)	Growth technique	Target used	Growth geometry	Optical studies	Electrical studies	Local probe studies	Post-growth annealing	Ref.
25–54	DC sputtering	W	GLAD	transmittance, bandgap, refractive index	<i>I–V</i>	NA	400 °C	[1]
500	reactive DC magnetron sputtering	W	GLAD	NA	current response for gas sensing	NA	400 and 500 °C	[2]
100	pulsed DC magnetron sputtering	W	GLAD	none (only structural and morphological studies)	NA	NA	500 °C	[3]
270, 500	e-beam evaporation	WO ₃	GLAD	transmittance	<i>I–V</i>	NA	100, 200, 300, 350, and 400 °C	[4]
1000	reactive DC magnetron sputtering	W	GLAD	transmittance, refractive index, bandgap	NA	NA	NA	[5]
300	reactive DC magnetron sputtering	W	GLAD	transmittance	NA	NA	NA	[6]
6–120 nm	RF magnetron sputtering	WO ₃	GLAD	transmittance, bandgap	<i>I–V</i>	Local work function	400 °C	present work

References

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